V _{RRM}	=	6000 V
IFAVM	=	250 A
I _{FSM}	=	3.6 kA
V _{F0}	=	2.5 V
r _F	=	2.5 m Ω
V _{DClink}	=	3000 V

Fast Recovery Diode 5SDF 02D6002

PRELIMINARY

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- Patented free-floating silicon technology
- Low switching losses
- Optimized for use as snubber diode in high-voltage GTO converters
- Standard press-pack ceramic housing, hermetically cold-welded
- Cosmic radiation withstand rating

Blocking

V _{RRM}	Repetitive peak reverse voltage	6000 V	Half sine wave, $t_P = 10 \text{ ms}$, $f = 50 \text{ Hz}$		
I _{RRM}	Repetitive peak reverse current	≤ 50 mA	$V_R = V_{RRM_i} T_j = 125^{\circ}C$		
V _{DClink}	Permanent DC voltage for 100 FIT failure rate	3000 V	100% Duty	Ambient cosmic radiation	
		3800 V	5% Duty	at sea level in open air.	

Mechanical data (see Fig. 6)

E	Mounting force	min.		10 kN
F _m	m Mounting force			12 kN
а	Acceleration:			
	Device unclamped			50 m/s²
	Device clamped			200 m/s ²
m	Weight			0.25 kg
Ds	Surface creepage distance		\geq	30 mm
Da	Air strike distance		\geq	20 mm

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On-state (see Fig. 1, 2)

I _{FAVM}	Max. average on-state current	250 A	Half sine wave, $T_c = 85^{\circ}C$
I _{FRMS}	Max. RMS on-state current	400 A	
I _{FSM}	Max. peak non-repetitive	3.6 kA	tp = 10 ms Before surge:
	surge current	11.4 kA	$tp = 1 ms T_c = T_j = 125^{\circ}C$
∫l²dt	Max. surge current integral	65.10 ³ A ² s	tp = 10 ms After surge:
		65.10 ³ A ² s	tp = 1 ms $V_R \approx 0 V$
V_{F}	Forward voltage drop	≤ 5 V	I _F = 1000 A
V_{F0}	Threshold voltage	2.5 V	Approximation for $T_j = 125^{\circ}C$
r _F	Slope resistance	2.5 mΩ	I _F = 2004000 A

Turn-on (see Fig. 3, 4)

Turn-off (see Fig. 5)

Irr	Reverse recovery current	\leq	260 A	di/dt = 100 A/ μ s,	T _j =125 °C,
Q _{rr}	Reverse recovery charge	\leq	2000 µC	I _F = 1000 A,	$V_{RM} = V,$
Err	Turn-off energy	\leq	J	R _s = 22 Ω,	$C_{\rm S} = 0.22 \mu {\rm F}$

Thermal (see Fig. 7)

Tj	Operating junction temperature range	-40125°C			
T _{stg}	Storage temperature range	-4	0125°C		
R_{thJC}	Thermal resistance junction to case	≤	80 K/kW	Anode side cooled	
		\leq	80 K/kW	Cathode side cooled	F _M =
		\leq	40 K/kW	Double side cooled	10… 12 kN
R_{thCH}	Thermal resistance case to heatsink	≤	16 K/kW	Single side cooled	
		\leq	8 K/kW	Double side cooled	

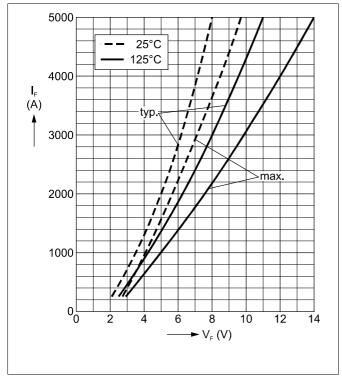


Fig. 1 Forward current vs. forward voltage (typ. and max. values).

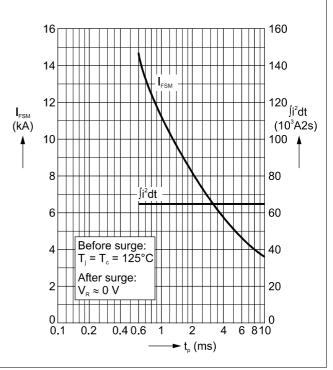


Fig. 2 Surge current and fusing integral vs. pulse width (max. values) for non repetitive, half-sinusoidal surge current pulses.

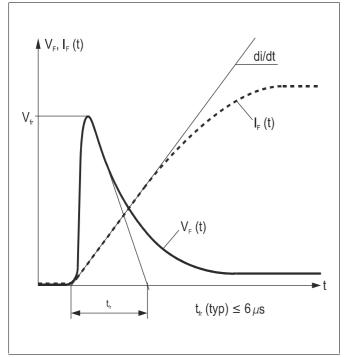


Fig. 3 Typical forward voltage waveform when the diode is turned on with a high di/dt.

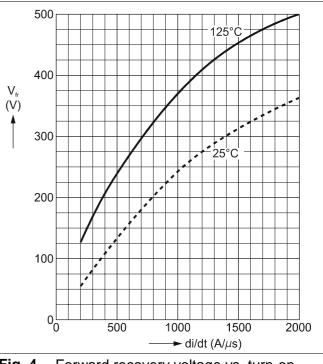


Fig. 4 Forward recovery voltage vs. turn-on di/dt (max. values).

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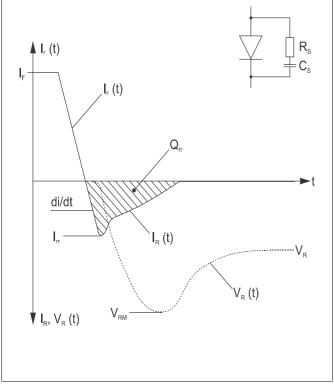
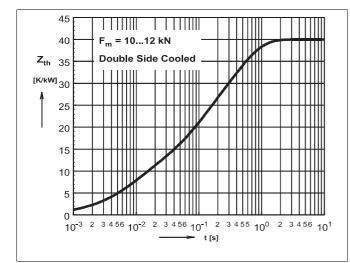


Fig. 5 Typical current and voltage waveforms at turn-off with conventional RC snubber circuit



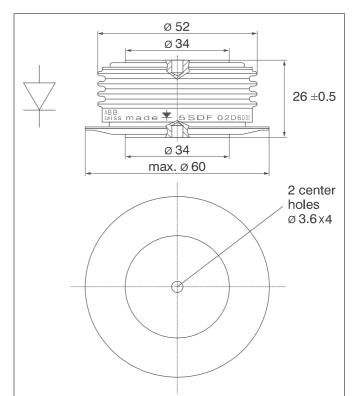


Fig. 6 Outline drawing. All dimensions are in millimeters and represent nominal values unless stated otherwise.

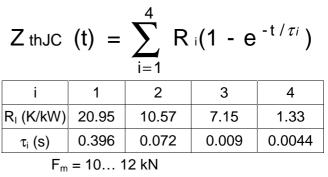




Fig. 7 Transient thermal impedance (junction to case) vs. time in analytical and graphical form (max. values).

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